

IN THE CLAIMS:

1. Cancelled.
2. Cancelled.
3. Cancelled.
4. Cancelled.
5. Cancelled.
6. Cancelled.
7. Cancelled.
8. (THRICE AMENDED) The A printed circuit board unit comprising:
a printed circuit board;
an electronic component;
a solder bump interposed between the printed circuit board and the electronic component so
as to fix the electronic component to the printed circuit board; and

an interposer disposed between the printed circuit board and the electronic component so as to define a through hole for containing the solder bump wherein

at least an inner surface of the through hole is covered with a coating wet to a melted state of the solder bump, said coating being spaced from an outer periphery of the solder bump.

9. Cancelled.

10. Withdrawn.

11. Withdrawn.

12. Withdrawn.

13. Withdrawn.

14. Withdrawn.

15. Withdrawn.

16. Cancelled.

17. (NEW) The printed circuit board unit according to claim 8, wherein said interposer is spaced from at least one of the printed circuit board and the electronic component